

Product Change Notification - KSRA-08URFH931

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Date:

12 Feb 2018

Product Category:**Notification subject:**

CCB 3090 Initial Notice: Qualification of ASE as a new assembly site for selected products of the 0.11 wafer technology at DBHU available in 64L VQFN (8x8x.09 mm) package.

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_{_Affected_CPN}.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for selected products of the 0.11 wafer technology at DBHU available in 64L VQFN (8x8x.09 mm) package.

Pre Change:

Assembled at TICP

Post Change:

Assembled at ASE

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp / TICP	ASE Inc. / ASE

Wire material	Au wire	Au Wire
Die attach material	EN4900	EN4900
Molding compound material	G631	G631
Lead frame material	C 194	C 194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying ASE as new assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

March 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2018				March 2018				
Workweek	05	06	07	08	09	10	11	12	13
Initial PCN Issue Date			X						
Qual Report Availability					X				
Final PCN Issue Date						X			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

February 12, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-08URFH931_Affected CPN.pdf](#)

[PCN_KSRA-08URFH931_Qual Plan.pdf](#)

[PCN_KSRA-08URFH931_Affected CPN.xlsx](#)

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